



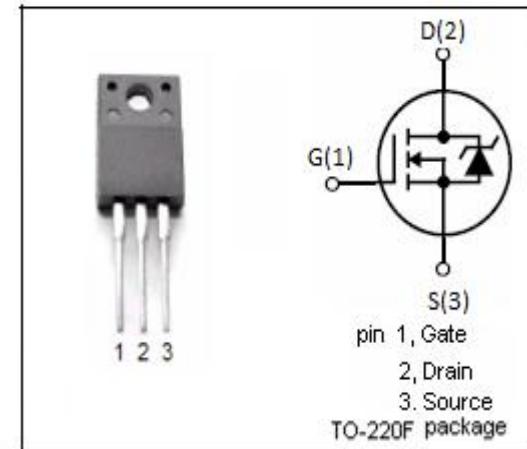
INCHANGE Semiconductor

isc N-Channel MOSFET Transistor

SPA07N65C3

• FEATURES

- New revolutionary high voltage technology
- Ultra low gate charge
- High peak current capability
- Improved transconductance
- 100% avalanche tested
- Minimum Lot-to-Lot variations for robust device performance and reliable operation



• APPLICATIONS

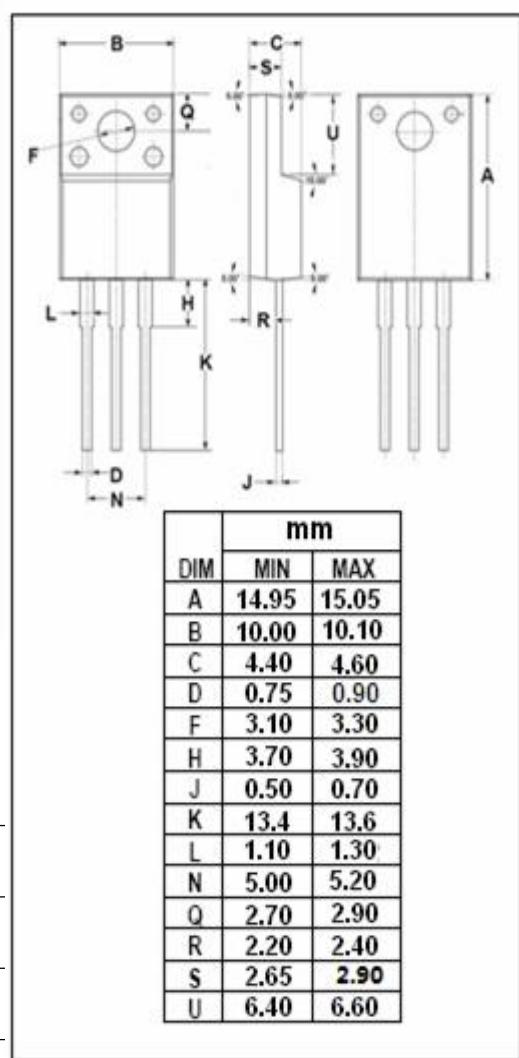
- Switching applications

• ABSOLUTE MAXIMUM RATINGS($T_a=25^\circ\text{C}$)

SYMBOL	PARAMETER	VALUE	UNIT
V_{DSS}	Drain-Source Voltage	650	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Drain Current-Continuous@ $T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$	7.3 4.6	A
I_{DM}	Drain Current-Single Pulsed	21.9	A
P_D	Total Dissipation	32	W
T_j	Operating Junction Temperature	-55~150	°C
T_{stg}	Storage Temperature	-55~150	°C

• THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
$R_{th(ch-c)}$	Channel-to-case thermal resistance	3.9	°C/W
$R_{th(ch-a)}$	Channel-to-ambient thermal resistance	62	°C/W





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SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V; I _D = 0.25mA	650			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =±20V; I _D =0.35mA		3	3.9	V
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} = 10V; I _D =4.6A		540	600	mΩ
I _{GSS}	Gate-Source Leakage Current	V _{GS} = ±20V; V _{DS} = 0V			±0.1	μA
I _{DSS}	Drain-Source Leakage Current	V _{DS} = 650V; V _{GS} = 0V; T _J =25°C T _J =125°C			1 100	μA
V _{SDF}	Diode forward voltage	I _{SD} =7.3A, V _{GS} = 0 V			1.2	V